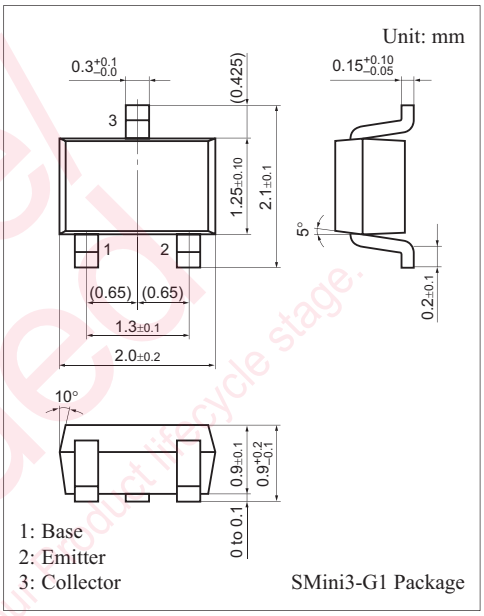
2SA2122

Silicon PNP epitaxial planar type

For general amplification
Complementary to 2SC5950

■ Features

- High forward current transfer ratio h_{FE}
- Smini typ package, allowing downsizing of the equipment and automatic insertion through the tape packing



Marking Symbol: 7L

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	−60	V
Collector-emitter voltage (Base open)	V_{CEO}	−50	V
Emitter-base voltage (Collector open)	V_{EBO}	−7	V
Collector current	I_C	−100	mA
Peak collector current	I_{CP}	−200	mA
Collector power dissipation	P_C	150	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = -10\ \mu A$, $I_E = 0$	−60			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = -2$ mA, $I_B = 0$	−50			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = -10\ \mu A$, $I_C = 0$	−7			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -20$ V, $I_E = 0$			− 0.1	μA
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = -10$ V, $I_B = 0$			−100	μA
Forward current transfer ratio	h_{FE}	$V_{CE} = -10$ V, $I_C = -2$ mA	160		460	—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = -100$ mA, $I_B = -10$ mA		− 0.2	− 0.5	V
Transition frequency	f_T	$V_{CB} = -10$ V, $I_E = 1$ mA, f = 200 MHz		80		MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = -10$ V, $I_E = 0$, f = 1 MHz		2.2		pF

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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